

**Listing of Claims**

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently amended) A method for manufacturing a dielectric barrier discharge type low-pressure discharge lamp comprising a tubular glass lamp vessel which is provided with an electrically conductive layer as an electrode on an outer surface of at least one end portion of the lamp vessel, comprising the steps of:

dipping said lamp vessel in an ultrasonic tub, wherein the electrically conductive layer is composed of solder material on the surface of the lamp vessel, and attaching a metal member for electric power supply is attached on to the electrically conductive layer by ultrasonic soldering.

2. (Currently amended) A method of manufacturing a dielectric barrier discharge type low-pressure discharge lamp according to claim 1, wherein the major component of the solder material is one selected from the group consisting of tin, an alloy of tin and indium, and an alloy of tin and bismuth, and the electrically conductive layer is formed by dipping the solder material in an ultrasonic solder tub.

3. (Currently amended) A method of manufacturing a dielectric barrier discharge type low-pressure discharge lamp according to claim 1, wherein the metal member is a metal strip.

4. (Currently amended) A method of manufacturing a dielectric barrier discharge type low-pressure discharge lamp according to claim 2, wherein the metal member is a metal wire which is wound around the electrically conductive layer in a coil shape and attached by soldering.

5. (Currently amended) A method of manufacturing a dielectric barrier discharge type low-pressure discharge lamp according to claim 1, wherein the metal member is a metal wire which is wound around the electrically conductive layer in a coil shape and attached by soldering.

6. (Canceled)

7. (Currently amended) A method of manufacturing a dielectric barrier discharge type low-pressure discharge lamp comprising a tubular glass lamp vessel which is provided with an electrically conductive layer as an electrode on an outer surface of at least one end portion of the lamp vessel, comprising the steps of:

dipping said lamp vessel in an ultrasonic tub, wherein the electrically conductive layer is composed of solder material on the surface of the lamp vessel, and attaching a core wire of a lead wire is attached by soldering onto the electrically conductive layer by ultrasonic soldering.

8. (Canceled)

9. (New) A method of manufacturing a discharge lamp, comprising the steps of:  
depositing an ionizable filling material into a lamp vessel;

sealing said lamp vessel

dipping a portion of said lamp vessel into a solder tub containing molten solder material; and

applying ultrasonic vibration to the molten solder to form an electrically conductive layer on said portion of said lamp vessel.

10. (New) The method of claim 9, further comprising the step of:

performing blast treatment on said portion of said lamp vessel before said step of dipping.

11. (New) The method of claim 9, wherein said vessel is sealed prior to said

dipping.

12. (New) The method of claim 9, wherein said lamp vessel is tubular in shape

and has two ends, and said step of dipping a portion of said lamp vessel dips a first of said ends into said solder tub.

13. (New) The method of claim 9, further comprising the steps of:

attaching a metal strip to said conductive layer using ultrasonic soldering; and

entwining an electrical lead with said metal strip.

14. (New) The method of claim 9, further comprising the steps of:

coiling a metal wire around said portion of said lamp vessel and said conductive layer; and

attaching said coiled metal wire to said conductive layer using ultrasonic soldering.

15. (New) The method of claim 9, further comprising the step of:

attaching a core wire of a lead wire to said conductive layer using ultrasonic soldering.

16. (New) The method of claim 9, wherein said portion of said lamp vessel is an end

portion, and further comprising the step of:

attaching a core wire of a lead wire to a top end of said end portion using ultrasonic soldering.

17. (New) The method of claim 9, further comprising the steps of:

winding a stripped core wire portion of a lead wire around an outer periphery of said portion of said lamp vessel; and

attaching said stripped core wire portion to said conductive layer using ultrasonic soldering.

18. (New) The method of claim 9, further comprising the step of:

attaching two metal leads to said conductive layer using ultrasonic soldering, wherein said lamp vessel is tubular in shape having two ends, said portion of said lamp vessel is one of said ends, and whereby said discharge lamp has two leads on one end.

19. (New) The method of claim 9, wherein said solder material is tin, an alloy of tin and indium, or an alloy of tin and bismuth.

20. (New) The method of claim 19, wherein said solder material further includes antimony, zinc or aluminum as an additive.